



NPN SURFACE MOUNT DARLINGTON TRANSISTOR

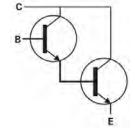
Features

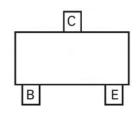
- 40V Darlington Transistor
- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching
- High Current Gain
- Ultra-Small Surface Mount Package
- Lead Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Note 2)

Mechanical Data

- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Weight: 0.006 grams (approximate)







Top View

Device symbol

Pin-out Top view

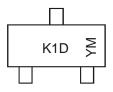
Ordering Information (Note 3)

ſ	Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
	MMST6427-7-F	K1D	7	8	3,000

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" Policy can be found on our website at http://www.diodes.com
- 3. For Packaging Details, go to our website at http://www.diodes.com.

Marking Information



K1D= Product Type Marking Code YM = Date Code Marking Y = Year ex: X = 2010 M = Month ex: 9 = September

Date Code Key

Year	20	10	20	11	20	12	20	13	20	14	20	15
Code	>	<	`	Y	2	7	,	4	[3	(2
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	40	V
Collector-Emitter Voltage	V _{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	12	V
Collector Current - Continuous (Note 4)	I _C	500	mA
Power Dissipation (Note 4)	P _d	200	mW
Thermal Resistance, Junction to Ambient (Note 4)	$R_{ heta JA}$	625	°C/W
Operating and Storage Temperature Range	T_{j} , T_{STG}	-55 to +150	°C

Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 5)						
Collector-Base Breakdown Voltage	BV _{CBO}	40	_	V	$I_C = 100 \mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage	BV_{CEO}	40		V	$I_C = 10 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	BV _{EBO}	12		V	$I_E = 10 \mu A, I_C = 0$	
Collector Cutoff Current			50	nA	$V_{CB} = 30V, I_{E} = 0$	
Collector Cutoff Current			1.0	μΑ	$V_{CE} = 25V, I_B = 0$	
Emitter Cutoff Current		_	50	nA	$V_{EB} = 10V, I_C = 0$	
Emitter Cutoff Current $ I_{EBO} $ — 50 nA $ V_{EB} = 10V$, $I_C = 0$ ON CHARACTERISTICS (Note 5)						
DC Current Gain	h _{FE}	10,000 20,000 14,000	100,000 200,000 140,000	_	$I_C = 10mA$, $V_{CE} = 5.0V$ $I_C = 100mA$, $V_{CE} = 5.0V$ $I_C = 500mA$, $V_{CE} = 5.0V$	
Collector-Emitter Saturation Voltage		_	1.2 1.5	٧	$I_C = 50$ mA, $I_B = 0.5$ mA $I_C = 500$ mA, $I_B = 0.5$ mA	
Base-Emitter Saturation Voltage	V _{BE(sat)}	_	2.0	V	$I_C = 500 \text{mA}, I_B = 0.5 \text{mA}$	
Base-Emitter On Voltage			1.75	V	$I_C = 50 \text{mA}, V_{CE} = 5.0 \text{V}$	
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance		8.0 Typical		рF	$V_{CB} = 10V$, $f = 1.0MHz$, $I_E = 0$	
Input Capacitance		15 Typical		рF	$V_{EB} = 0.5V$, $f = 1.0MHz$, $I_C = 0$	

Device mounted on 25mm x 22 mm x 1.6mm FR4 PCB, 1oz copper, singled sided
Short duration pulse test used to minimize self-heating effect.



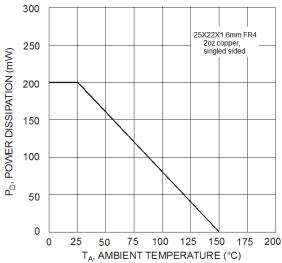


Fig. 1, Max Power Dissipation vs. Ambient Temperature

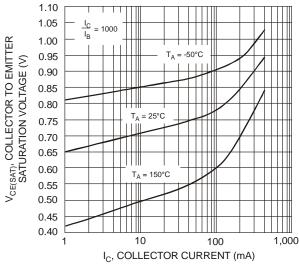
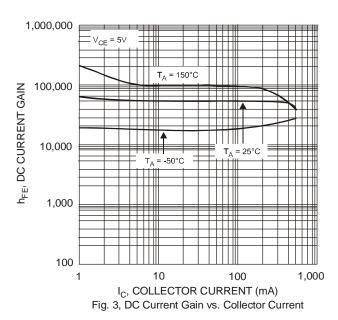


Fig. 2, Collector Emitter Saturation Voltage vs. Collector Current



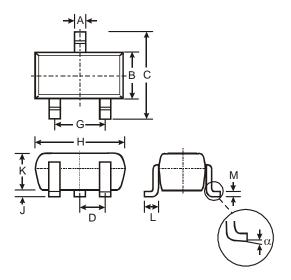
1,000 V_{CE} = 5V WINDMIDH BROWNDH HOUSE TO THE PROPERTY (WHY) 100 I_C, COLLECTOR CURRENT (mA)

1.6 1.5 1.4 $V_{\text{BE}(\text{ON})}$, BASE EMITTER VOLTAGE (V) 1.3 1.2 $T_A = 25^{\circ}C$ 1.1 1.0 0.9 0.8 T_A = 150°C 0.7 0.6 0.5 0.4 0.3 0.2 0.1 100 I_{C} , COLLECTOR CURRENT (mA)

Fig. 4, Base Emitter Voltage vs. Collector Current

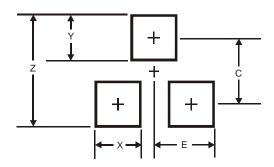


Package Outline Dimensions



SOT323						
Dim	Min	Max	Тур			
Α	0.25	0.40	0.30			
В	1.15	1.35	1.30			
C	2.00	2.20	2.10			
D	-	-	0.65			
G	1.20	1.40	1.30			
Н	1.80	2.20	2.15			
7	0.0	0.10	0.05			
K	0.90	1.00	1.00			
١	0.25	0.40	0.30			
M	0.10	0.18	0.11			
α	0°	8°	-			
All Dimensions in mm						

Suggested Pad Layout



Dimensions	Value (in mm)				
Z	2.8				
Х	0.7				
Υ	0.9				
С	1.9				
E	1.0				



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